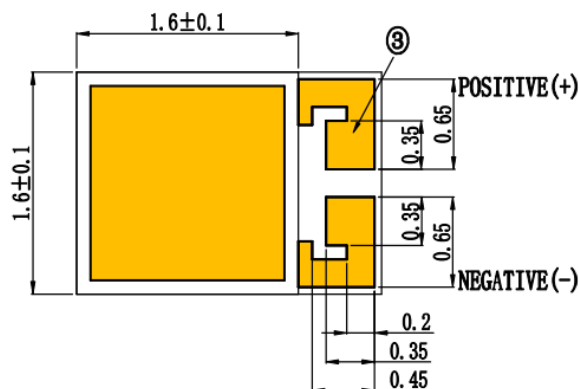
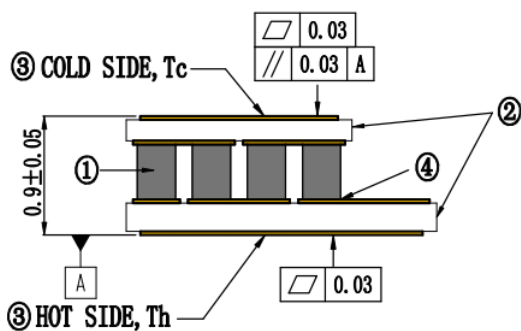
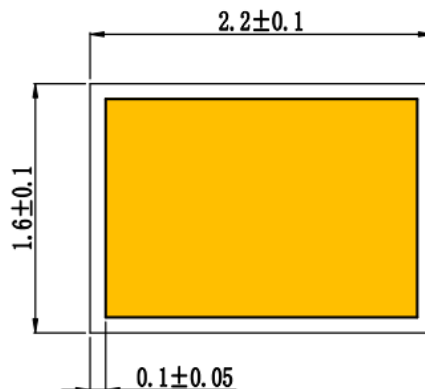
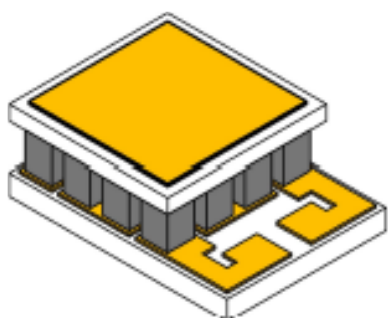


Product Code: TEM1-00812B

1. 组件尺寸(mm) Module Dimensions



2. 电参数 Electrical Parameters

性能参数								
Th=27°C				Th=50°C				Ta=27°C
$\Delta T_{max}/^{\circ}C$	Qc max/W	Umax/V	I _{max} /A	$\Delta T_{max}/^{\circ}C$	Qc max/W	Umax/V	I _{max} /A	ACR/Ω
70	0.64	0.96	1.09	79	0.68	1.03	1.09	0.66±10%

3. 标注信息 Graphic Notes

- 半导体材料：碲化铋 Bi_2Te_3 alloy
Thermoelectric material: Bismuth Telluride
- 陶瓷基板：AlN 白色
Ceramic plate: AlN white color
- 金属化层组成：Cu/Ni/Pd/Au, Au 厚度: 0.1-0.15um
Metallic layers: Cu/Ni/Pd/Au, Au thickness: 0.1-0.15um
- 内部焊料组成：AuSn; 最高允许工艺温度 265 摄氏度, 2 分钟
Interior solder composition: AuSn, Max. process temperature 265 Celsius Degree for 2 min.